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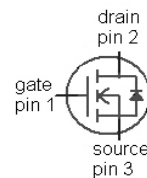
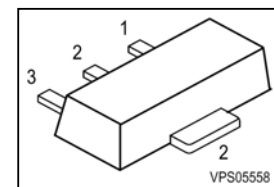


SIPMOS® Small-Signal-Transistor
Feature

- n-channel
- enhancement mode
- Logic level
- dv/dt rated
- Qualified according to AEC Q101
- Halogen-free according to IEC 61249-2-21

Product Summary

$V_{DS}^{1)}$	600	V
$R_{DS(on),max}$	45	Ω
I_D	0.09	A


SOT89


Type	Package	Pb-free	Tape and Reel Information	Marking
BSS225	SOT89	Yes	H6327: 3000PCS/reel	KD

Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$T_A=25\text{ }^\circ\text{C}$	0.09	A
		$T_A=70\text{ }^\circ\text{C}$	0.073	
Pulsed drain current	$I_{D,pulse}$	$T_A=25\text{ }^\circ\text{C}$	0.36	
Reverse diode dv/dt	dv/dt	$I_D=0.09\text{ A}$, $V_{DS}=480\text{ V}$, $di/dt=200\text{ A}/\mu\text{s}$, $T_{j,max}=150\text{ }^\circ\text{C}$	6	kV/ μs
Gate source voltage	V_{GS}		± 20	V
ESD Class JESD22-A114-HBM			Class 1a	
Power dissipation	P_{tot}	$T_A=25\text{ }^\circ\text{C}$	1.00	W
Operating and storage temperature	T_j, T_{stg}		-55 ... 150	$^\circ\text{C}$
IEC climatic category; DIN IEC 68-1			55/150/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Thermal characteristics

Thermal resistance, junction - minimal footprint	R_{thJA}		-	-	125	K/W
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Electrical characteristics, at $T_j=25\text{ °C}$, unless otherwise specified
Static characteristics

Drain-source breakdown voltage ¹⁾	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}, I_D=250\text{ }\mu\text{A}$	600	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}; I_D=94\text{ }\mu\text{A}$	1.3	1.9	2.3	
Drain-source leakage current	$I_{D(off)}$	$V_{DS}=600\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ °C}$	-	-	0.1	μA
		$V_{DS}=600\text{ V}, V_{GS}=0\text{ V}, T_j=150\text{ °C}$	-	-	5	
Gate-source leakage current	I_{GSS}	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	-	10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=4.5\text{ V}, I_D=0.09\text{ A}$	-	30	45	Ω
		$V_{GS}=10\text{ V}, I_D=0.09\text{ A}$	-	28	45	
Transconductance	g_{fs}	$ V_{DS} >2 I_D R_{DS(on)max}, I_D=0.075\text{ A}$	0.05	0.14	-	S

¹⁾ V_{DS} is zero-hour rated, see note at p.8

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$ $f=1\text{ MHz}$	-	99	131	pF
Output capacitance	C_{oss}		-	7.6	11	
Reverse transfer capacitance	C_{rss}		-	3.1	4.4	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=300\text{ V},$ $V_{GS}=10\text{ V}, I_D=0.09\text{ A},$ $R_G=6\ \Omega$	-	14.0	20.0	ns
Rise time	t_r		-	38.0	57.0	
Turn-off delay time	$t_{d(off)}$		-	62.0	93	
Fall time	t_f		-	41.0	62	

Gate Charge Characteristics

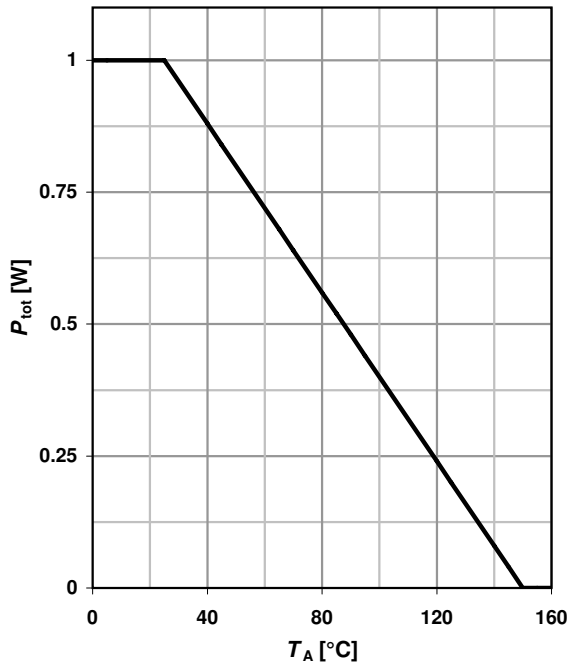
Gate to source charge	Q_{gs}	$V_{DD}=400\text{ V},$ $I_D=0.09\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	0.32	0.43	nC
Gate to drain charge	Q_{gd}		-	1.4	2.1	
Gate charge total	Q_g		-	3.9	5.8	
Gate plateau voltage	$V_{plateau}$		-	3.3	-	V

Reverse Diode

Diode continuous forward current	I_S	$T_A=25\text{ }^\circ\text{C}$	-	-	0.09	A
Diode pulse current	$I_{S,pulse}$		-	-	0.36	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=0.09\text{ A},$ $T_j=25\text{ }^\circ\text{C}$	-	0.75	1.2	V
Reverse recovery time	t_{rr}	$V_R=300\text{ V}, I_F=0.09\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	246	370	ns
Reverse recovery charge	Q_{rr}		-	248	373	

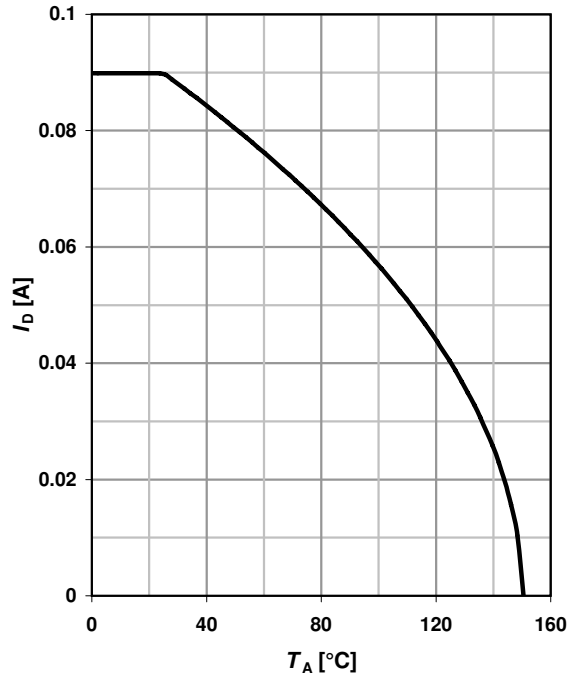
1 Power dissipation

$$P_{\text{tot}} = f(T_A)$$



2 Drain current

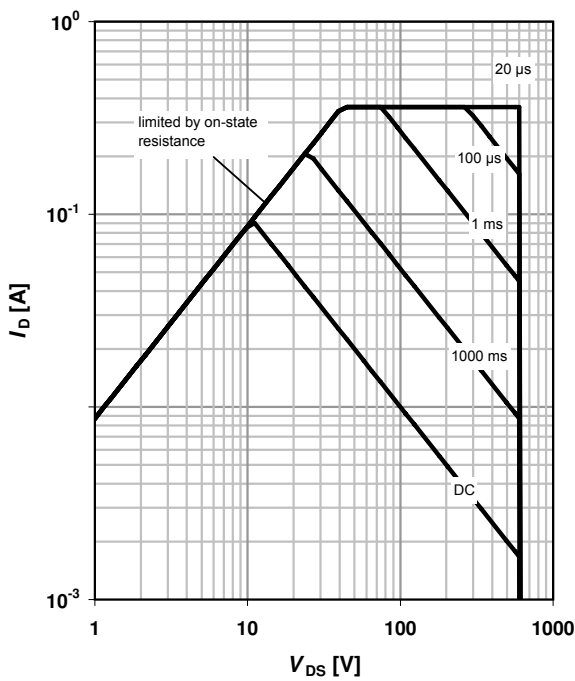
$$I_D = f(T_A); V_{GS} \geq 10 \text{ V}$$



3 Safe operating area

$$I_D = f(V_{DS}); T_A = 25 \text{ °C}; D = 0$$

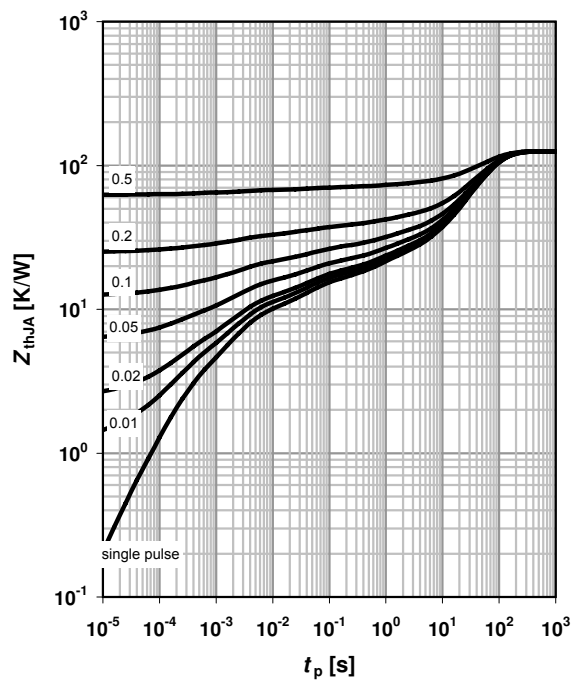
parameter: t_p



4 Max. transient thermal impedance

$$Z_{\text{thJA}} = f(t_p)$$

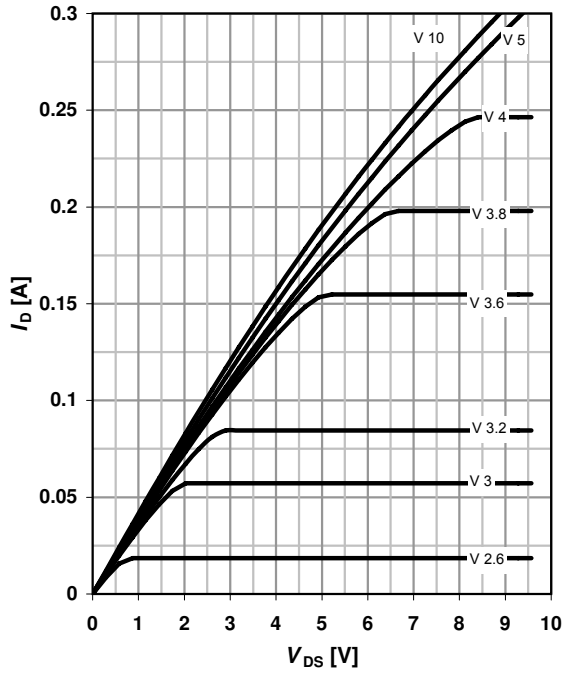
parameter: $D = t_p / T$



5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

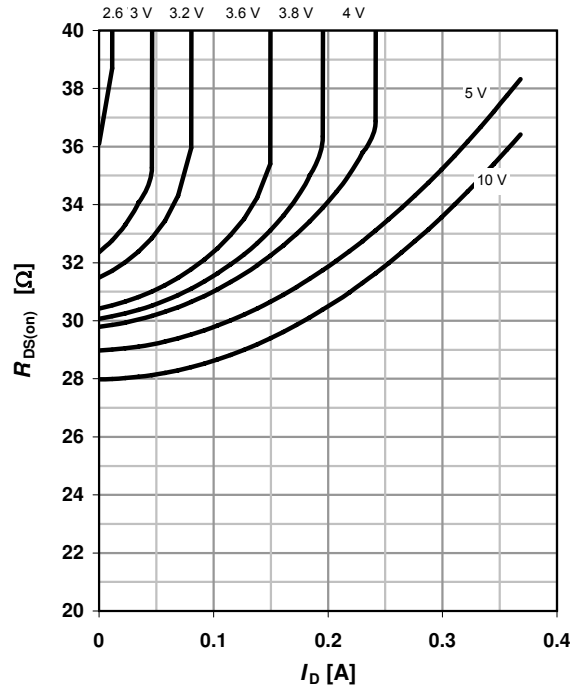
parameter: V_{GS}



6 Typ. drain-source on resistance

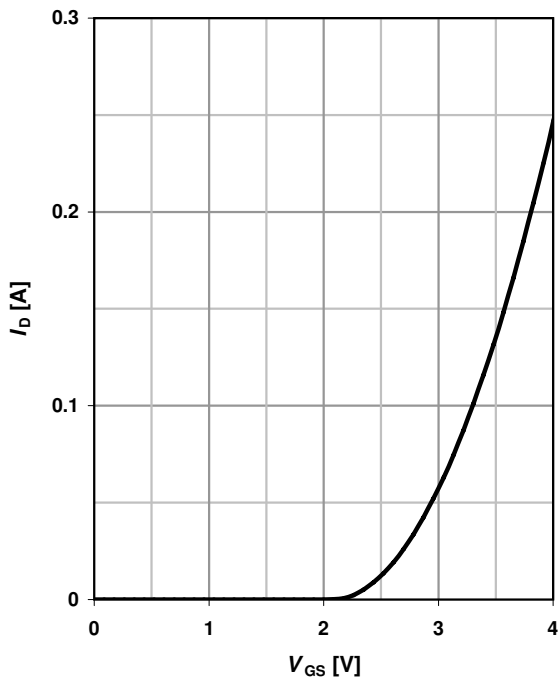
$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

parameter: V_{GS}



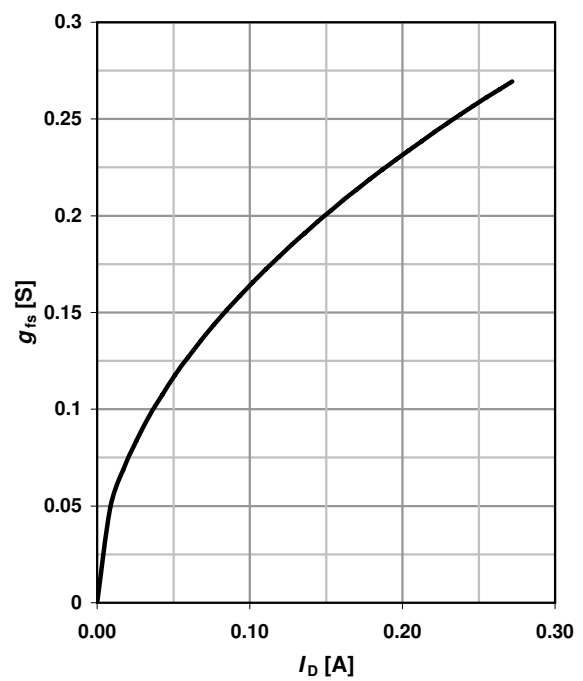
7 Typ. transfer characteristics

$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$



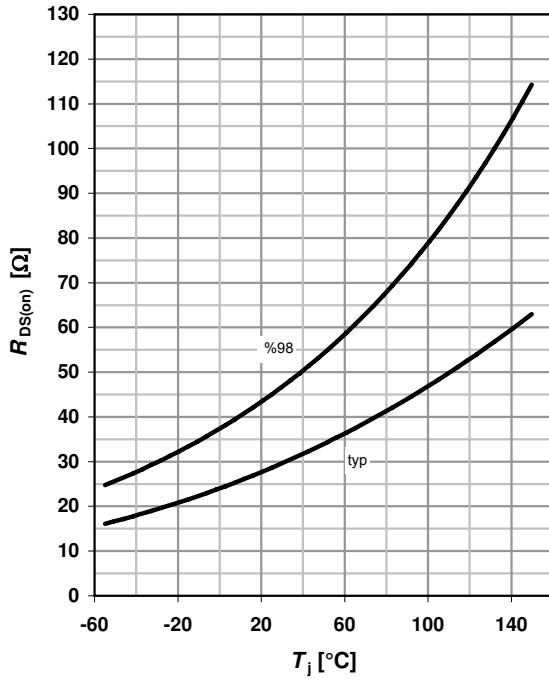
8 Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25\text{ }^\circ\text{C}$



9 Drain-source on-state resistance

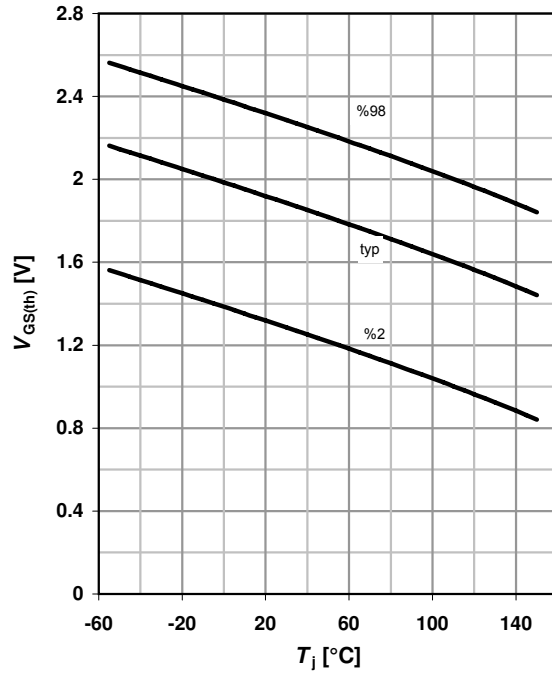
$R_{DS(on)} = f(T_j); I_D = 0.1 \text{ A}; V_{GS} = 10 \text{ V}$



10 Typ. gate threshold voltage

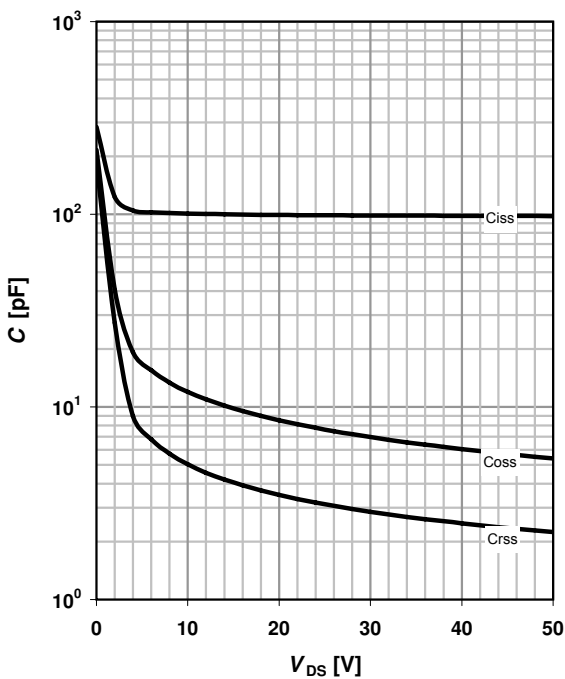
$V_{GS(th)} = f(T_j); V_{DS} = V_{GS}; I_D = 94 \mu\text{A}$

parameter: I_D



11 Typ. capacitances

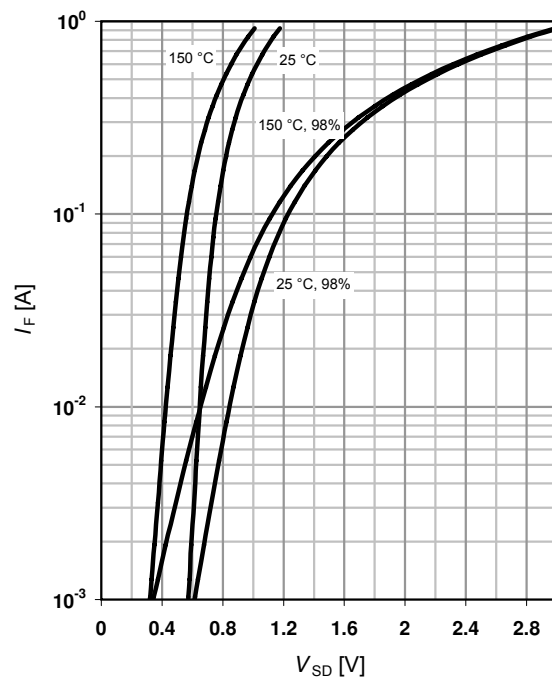
$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}; T_j = 25^\circ\text{C}$



12 Forward characteristics of reverse diode

$I_F = f(V_{SD})$

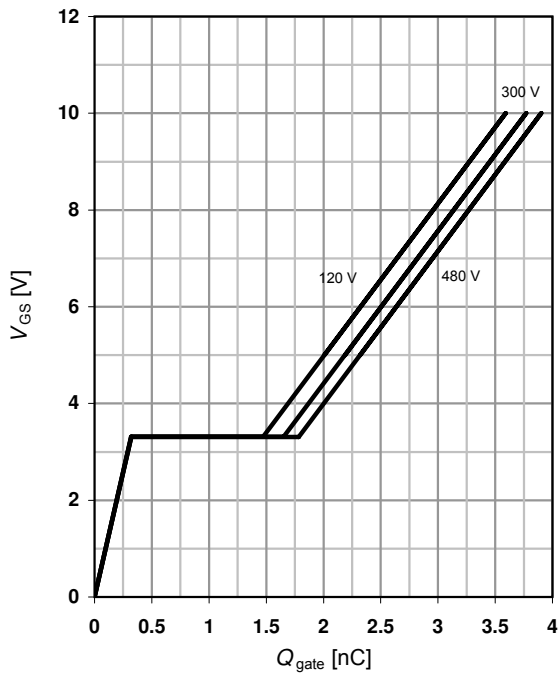
parameter: T_j



13 Typ. gate charge

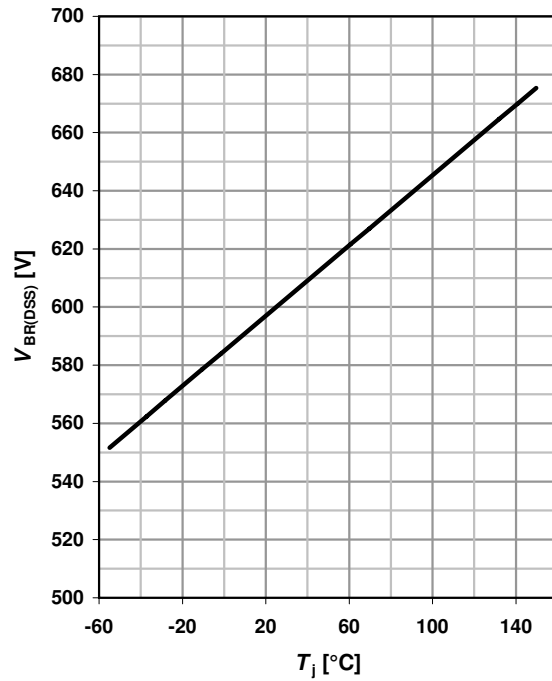
$$V_{GS} = f(Q_{gate}); I_D = 0.1 \text{ A pulsed}$$

parameter: V_{DD}



14 Drain-source breakdown voltage

$$V_{BR(DSS)} = f(T_j); I_D = 250 \mu\text{A}$$



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